

PRODUCT AND PROCESS CHANGE NOTIFICATION

Generic Copy

ISSUE DATE: 10-Oct-2013

NOTIFICATION: 15814

MKL05Z32,MKL25Z128,MKL02Z32,MKL26Z128 QFN Assembly TITLE:

Capacity Expansion to ASE-CL

EFFECTIVE

08-Jan-2014 DATE:

DEVICE(S)

MPN
MKL02Z16VFK4
MKL02Z16VFM4
MKL02Z32VFK4
MKL02Z32VFK4R
MKL02Z32VFM4
MKL04Z16VFK4
MKL04Z16VFM4
MKL04Z32VFK4
MKL04Z32VFM4
MKL04Z32VFM4R
MKL04Z8VFK4
MKL04Z8VFM4
MKL05Z16VFK4
MKL05Z16VFM4
MKL05Z32VFK4
MKL05Z32VFM4
MKL05Z32VFM4R
MKL05Z8VFK4
MKL05Z8VFM4
MKL14Z32VFM4
MKL14Z64VFM4
MKL14Z64VFM4R
MKL15Z128VFM4
MKL15Z32VFM4
MKL15Z64VFM4
MKL15Z64VFM4R

MKL16Z128VFM4 MKL16Z64VFM4 MKL24Z32VFM4 MKL24Z64VFM4 MKL25Z128VFM4 MKL25Z32VFM4 MKL25Z32VFM4 MKL25Z32VFM4 MKL25Z32VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z128VFM4		
MKL16Z64VFM4 MKL24Z32VFM4 MKL24Z64VFM4 MKL25Z128VFM4 MKL25Z32VFM4 MKL25Z64VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z128VFM4	MKL16Z128VFM4	
MKL24Z32VFM4 MKL24Z64VFM4 MKL25Z128VFM4 MKL25Z32VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z32VFM4	MKL16Z32VFM4	
MKL24Z64VFM4 MKL25Z128VFM4 MKL25Z32VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z32VFM4	MKL16Z64VFM4	
MKL25Z128VFM4 MKL25Z32VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z32VFM4	MKL24Z32VFM4	
MKL25Z32VFM4 MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z32VFM4	MKL24Z64VFM4	
MKL25Z64VFM4 MKL26Z128VFM4 MKL26Z32VFM4	MKL25Z128VFM4	
MKL26Z128VFM4 MKL26Z32VFM4	MKL25Z32VFM4	
MKL26Z32VFM4	MKL25Z64VFM4	
	MKL26Z128VFM4	
MKL26Z64VFM4	MKL26Z32VFM4	
	MKL26Z64VFM4	

AFFECTED CHANGE CATEGORIES

ASSEMBLY SITE

DESCRIPTION OF CHANGE

Freescale Semiconductor is announcing the assembly site expansion for the products listed in this notification, from the current Freescale FSL-TJN-FM, Tianjin, China assembly Facility to the ASE-CHUNGLI, TAIWAN (ASECL) Facility, which has been qualified as an additional assembly site for the products listed in notification.

REASON FOR CHANGE

Qualification of the ASE-CHUNGLI, TAIWAN (ASECL) assembly Facility to improve manufacturing flexibility and customer support.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact on device form, fit, function or reliability.

Freescale will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a **Service Request**.

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 15-Nov-2013

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

Freescale Semiconductor Manufacturing standard specification for assembly transfers was followed for the Assembly Transfer.

RELIABILITY DATA SUMMARY:

Will provide per request.

ELECTRICAL CHARACTERISTIC SUMMARY:

Comparison between Freescale FSL-TJN-FM, Tianjin, China and ASE-CHUNGLI, TAIWAN (ASECL) will be completed. Report will provide per the request.

CHANGED PART IDENTIFICATION:

For both 4X4 QFN and 5X5 QFN, the assembly site, among other information, is reflected in the package trace code.

The format for the Freescale standard trace code: ALYWZ is the following:

A=Assembly Site, L=Wafer Lot, Y=Year, W=Work Week,Z=Z CODE.

The current assembly site marking for FSL-TJN-FM is A=4.

The marking for proposed assembly ASECL is A=X.

|--|

ATTACHMENT(S):

N/A